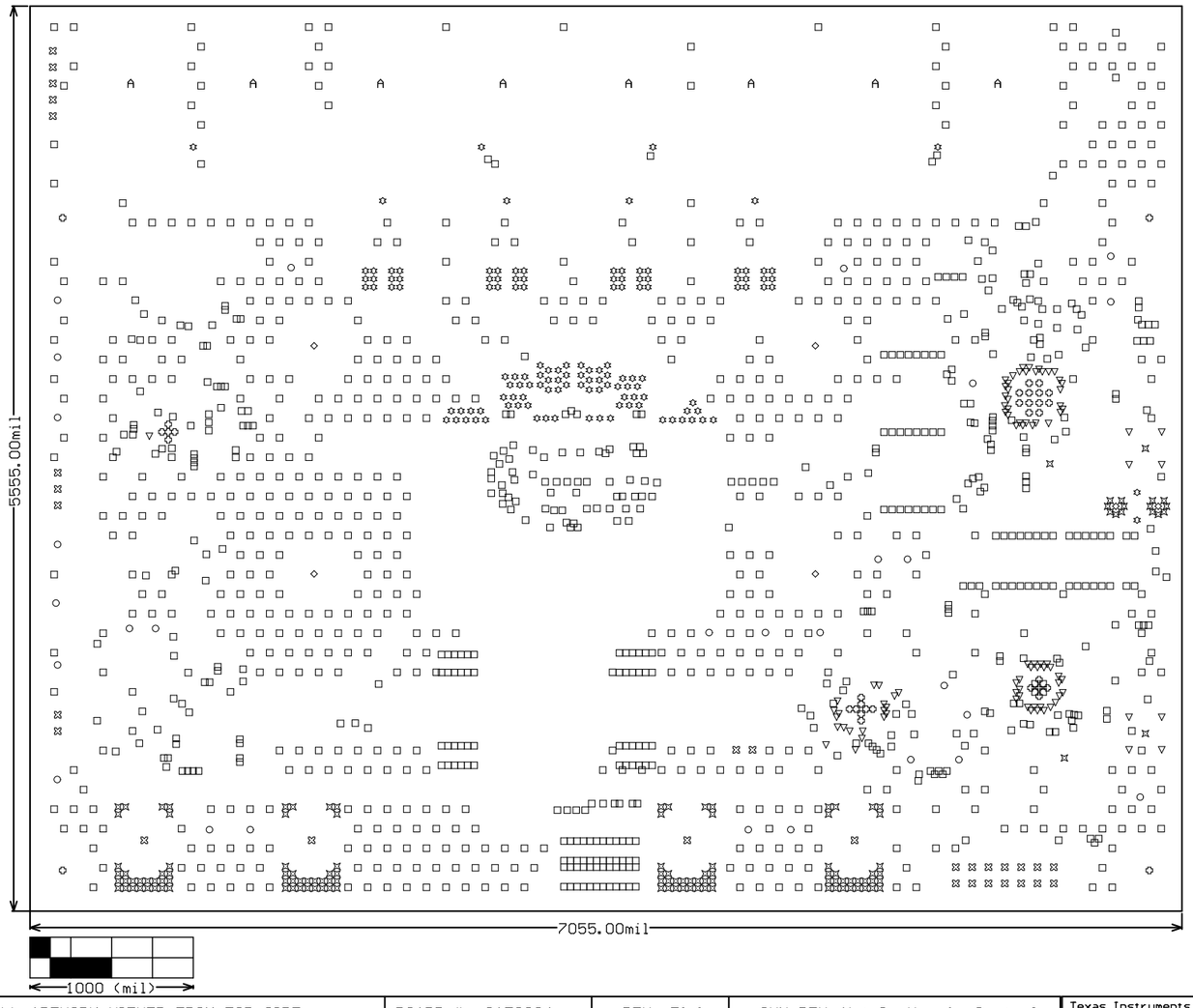

Top layer contains 100 Ohm differential pairs, 9mil trace, 5 mil spacing
Layer 3 contains 50 Ohm single ended high-speed lines, 7mil trace
Bottom layer contains 100 Ohm differential pair, 9mil trace, 5 mil spacing

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	30	7.874mil (0.2mm)	PTH	Round
▽	81	8mil (0.203mm)	PTH	Round
◇	2	9.842mil (0.25mm)	PTH	Round
□	1180	10mil (0.254mm)	PTH	Round
○	1	12mil (0.305mm)	PTH	Round
⌑	128	16mil (0.406mm)	PTH	Round
✡	128	22mil (0.559mm)	PTH	Round
⊠	26	40mil (1.016mm)	PTH	Round
⌑	2	59.055mil (1.5mm)	PTH	Round
○	27	63mil (1.6mm)	PTH	Round
✡	2	66.929mil (1.7mm)	PTH	Round
□	2	66.929mil (1.7mm)	NPTH	Round
▽	8	74.803mil (1.9mm)	PTH	Round
○	4	125.984mil (3.2mm)	PTH	Round
◇	4	130mil (3.302mm)	PTH	Round
⊠	4	188mil (4.775mm)	PTH	Round
⌂	8	265mil (6.731mm)	PTH	Round
	1637 Total			

Drill Table

Layer Stack Up Detail for: SAT0084E1-1.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil				
			9.8mil	FR-4 high TG	4.20	Core
MidLayer1-GND	(.G1)	1.4mil				
			9.8mil	FR-4 high TG	4.20	PrePreg
MidLayer2-HiSp	(.G2)	1.4mil				
			9.8mil	FR-4 high TG	4.20	Core
MidLayer3-GND	(.G3)	1.4mil				
			9.8mil	FR-4 high TG	4.20	PrePreg
MidLayer4	(.G4)	1.4mil				
			9.8mil	FR-4 high TG	4.20	Core
Bottom Layer	(.GBL)	1.4mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
5555MIL X 7055MIL

Number of Layers : 6
MIN. TRACK WIDTH: 7 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: FPD-Link III Class-D Amplifier
DESIGNED FOR: Public Release
FILE NAME: SAT0084E1-1.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0084	REV: E1.1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 7/10/2014 3:22:44 PM	TEXAS INSTRUMENTS	

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ENGINEER: Viktor Schneigelberger	LAYOUT BY: Krypton Solutions/RS
SCALE: 1.09	ALTIUM DESIGNER VERSION: 10.0.0.27009